

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:  
HABA

Serial No.: 10/087,395

Filed: March 1, 2002

For: *Semiconductor Module*

Confirmation No. 7807

Art Unit: 2827

Examiner: Alcala, Jose H.

Attorney Docket No.: 9797-0081-999

RESTRICTION ELECTION AND AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the restriction requirement from the U.S. Patent and Trademark Office dated April 24, 2003. The period for reply is set to expire on May 24, 2003 which is timely filed on May 27, 2003 because May 24, 2003 falls on a Saturday, and May 26, 2003 is a Federal holiday. Please enter the following election and remarks into the file of the above identified application.

**RESTRICTION**

The Examiner has imposed a restriction between:

Group I. Claims 1-41, drawn to a printed circuit board with a particular substrate, classified in class 174, subclass 255.

Group II. Claims 42-43, drawn to a method of making a printed circuit board, classified in class 29, subclass 825.

The Examiner has also imposed a species restriction on Group I between:

Species 1:	Embodiment of Figure 1.
Species 2:	Embodiment of Figure 2.
Species 3:	Embodiment of Figure 3.
Species 4:	Embodiment of Figure 4.
Species 5:	Embodiment of Figure 5.
Species 6:	Embodiment of Figure 6.
Species 7:	Embodiment of Figure 7.
Species 8:	Embodiment of Figure 8.
Species 9:	Embodiment of Figure 9.
Species 10:	Embodiment of Figure 10.
Species 11:	Embodiment of Figure 11.

The Examiner also states that “[c]urrently no claim is generic.”

### **ELECTION**

Applicant elects to prosecute the claims of Group I. Applicant also elects Species 2. Claims 1-14 are readable on Species 2. New claims 44-58 are also readable on Species 2.

### **DISCUSSION**

Although the Examiner has indicated that the embodiment of Figure 1 and the embodiment of Figure 2 are two separate species, it is respectfully submitted that Figure 1 is merely a close-up cross-sectional view of the substrate that forms part of the semiconductor module shown in Figure 2. In fact, the specification explicitly states that “[t]he semiconductor module 200 includes a substrate 202 similar to the substrate 100 shown and described in relation to FIGURE 1.” *See* page 7, lines 28-31. Accordingly, it is respectfully requested that the Examiner reconsider the species restriction between Figures 1 and 2, as Figures 1 and 2 show the same embodiment of the invention.